

GLSVLSI 2020

Beijing, China, May 27-29, 2020

<http://www.glsvlsi.org/>

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The 30th edition of GLSVLSI will be held in Beijing, China. Original, unpublished papers describing research in the general areas of VLSI and hardware design are solicited. Please visit <http://www.glsvlsi.org/> for more information.

In addition to the traditional topic areas of GLSVLSI listed below, papers are solicited for a special theme of “**In-Memory Processing for future electronics**”.

Program Tracks:

- **VLSI Design:** ASIC and FPGA design, microprocessors/micro-architectures, embedded processors, analog/digital/mixed-signal systems, NoC, SoC, IoT, interconnects, memories, bio-inspired and neuromorphic circuits and systems, BioMEMs, lab-on-a-chip, biosensors, CAD tools for biology and biomedical systems, implantable and wearable devices.
- **VLSI Circuits and Power Aware Design:** analog/digital/mixed-signal circuits, RF and communication circuits, chaos/neural/fuzzy-logic circuits, high-speed/low-power circuits, temperature estimation/optimization, power estimation/optimization.
- **Computer-Aided Design (CAD):** hardware/software co-design, high-level synthesis, logic synthesis, simulation and formal verification, layout, design for manufacturing, algorithms and complexity analysis.
- **Testing, Reliability, Fault-Tolerance:** digital/analog/mixed-signal testing, reliability, robustness, static and dynamic defect- and fault-recoverability, variation-aware design.
- **Emerging Computing & Post-CMOS Technologies:** nanotechnology, quantum computing, approximate and stochastic computing, sensor and sensor networks, post CMOS VLSI.
- **Hardware Security:** trusted IC, IP protection, hardware security primitives, reverse engineering, hardware Trojan, side-channel analysis, CPS and IoT security.
- **VLSI for Machine Learning and Artificial Intelligence:** hardware accelerators for machine learning, novel architectures for deep learning, brain-inspired computing, big data computing, reinforcement learning, cloud computing for Internet-of-Things (IoT) devices.
- **Microelectronic Systems Education:** Pedagogical innovations using a wide range of technologies such as ASIC, FPGA, multicore, GPU, educational techniques including novel curricula and laboratories, assessment methods, distance learning, textbooks, and design projects, Industry and academic collaborative programs and teaching.

Paper submission deadline:

December 17, 2019 (9pm EST)

Acceptance Notification:

February 18, 2020

Camera-Ready Paper Due:

March 13, 2020

Paper Submission: Authors are invited to submit full-length (6 pages maximum), original, unpublished papers along with an abstract of at most 200 words. To enable blind review, the author list should be omitted from the main document. Previously published papers or papers currently under review for other conferences/journals should NOT be submitted and will not be considered. Electronic submission in PDF format to the <http://www.glsvlsi.org> website is required. Author and contact information (name, affiliation, mailing address, telephone, fax, e-mail) must be entered during the submission process.

Paper Format: Submissions should be in camera-ready two-column format, following the ACM proceedings specifications located at:

<http://www.acm.org/publications/proceedings-template>

and the classification system detailed at: <http://www.acm.org/publications/class-2012>

Paper Publication and Presenter Registration: Papers will be accepted for regular or poster presentation at the symposium. Every accepted paper MUST have at least one author registered to the symposium by the time the camera-ready paper is submitted; at least one of the authors is also expected to attend the symposium and present the paper.

